

METHOD FOR PRODUCING SEMICONDUCTOR DEVICE, AND WIRE-BONDING APPARATUS

ABSTRACT

A method of manufacturing a semiconductor device includes: a wire tail contacting step of lowering a bonding tool with a wire tail extending out of the tip thereof to bring the tip of the wire tail into contact with a bonding surface of the semiconductor device; a wire tail bending step of moving the bonding tool in a direction intersecting with the axial direction of the bonding tool (Z direction) to bend the wire tail with the tip of the wire tail in contact with the bonding surface; a first bonding step of lowering the bonding tool to form the wire tail into a predetermined shape such that the tip of the wire tail points upward; a wire looping step; a second bonding step; and a wire cutting step. This allows the wire tail to be formed easily and efficiently into a predetermined shape.

Fig. 3